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## CONFIRMATORY LICENSE

THERMAL LOAD LEVELING USING ANISOTROPIC MATERIALS Title of Invention:

CARLSON, Frederick M., et al. Inventor(s):

Filing Date 11-09-11 13/292,410 Patent Application Serial No:

Patent Number: Issue Date:

Name of Contractor (i.e. Contractor, Subcontractor, Grant, or Cooperative Agreement, as applicable):

Name of Contractor: Varian Semiconductor Equipment Associates, Inc.

DOE Contract No. (i.e. Contract, Subcontract, Grant, or Cooperative Agreement, as applicable):

DE-EE0000595

Contractor Docket No.: 2011-090 **DOE Case No.:** S-130,022

The Contractor has reported the above-identified invention as a Subject Invention to DOE and has elected to retain title thereto.

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Varian Semiconductor Equipment Associates, Inc. Contractor Name

Official's Name David H. Hwang

RECORDED: 04/16/2013

Official's Title General Counsel and Chief IP Counsel Business Address 35 Dory Road Gloucester, MA 01930

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